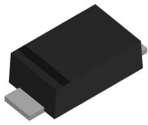


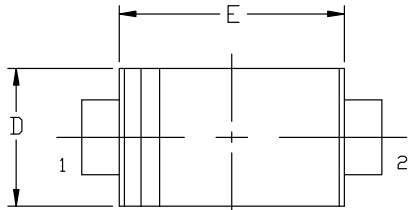
MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

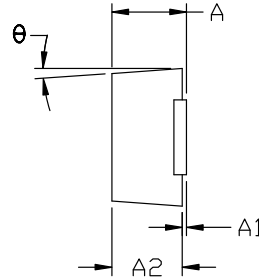


SOD-123-2 1.65x2.70x0.90
CASE 498
ISSUE E

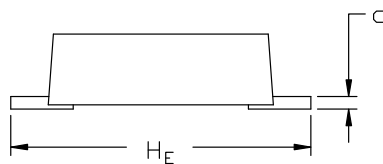
DATE 22 AUG 2023



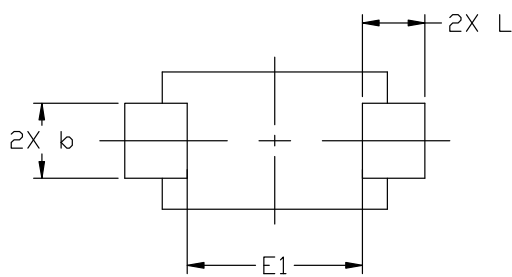
TOP VIEW



END VIEW

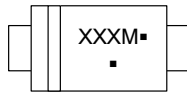


SIDE VIEW



BOTTOM VIEW

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code
 M = Date Code
 ■ = Pb-Free Package

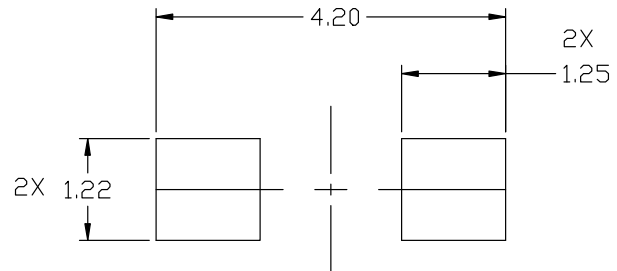
(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

DIM	MILLIMETERS		
	MIN.	NDM.	MAX.
A	0.90	0.95	0.98
A1	0.00	0.05	0.10
A2	0.85	0.90	0.95
b	0.70	0.90	1.10
c	0.10	0.15	0.20
D	1.50	1.65	1.80
E	2.50	2.70	2.90
E1	1.70	2.10	2.50
H _E	3.40	3.60	3.80
L	0.55	0.75	0.95
θ	0°	---	8°

NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSIONS b AND L ARE TO BE MEASURED ON A FLAT SECTION OF THE LEAD BETWEEN 0.10 AND 0.25 FROM THE LEAD TIP.
4. DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH PROTRUSIONS, OR GATE BURRS.
5. FLAT LEAD.



RECOMMENDED MOUNTING FOOTPRINT

* For additional information on our Pb-Free strategy and soldering details, please download the IN Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

DOCUMENT NUMBER:	98AON11184D	Electronic versions are uncontrolled except when accessed directly from the Document Repository. Printed versions are uncontrolled except when stamped "CONTROLLED COPY" in red.
DESCRIPTION:	SOD-123-2 1.65x2.70x0.90	PAGE 1 OF 1

onsemi and ONSEMI are trademarks of Semiconductor Components Industries, LLC dba onsemi or its subsidiaries in the United States and/or other countries. onsemi reserves the right to make changes without further notice to any products herein. onsemi makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does onsemi assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. onsemi does not convey any license under its patent rights nor the rights of others.